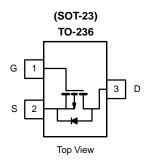
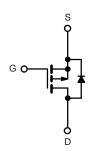


SM2421PSAN-VB Datasheet

P-Channel 30 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|------------------------------------|---------------------------------|-----------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}$ (Ω) Typ. | I _D (A) ^a | Q _g (Typ.) | | |
| | 0.046 at V _{GS} = - 10 V | - 5.6 | | | |
| - 30 | 0.049 at V _{GS} = - 6 V | - 5 | 11.4 nC | | |
| | 0.054 at V _{GS} = - 4.5 V | -4.5 | | | |





P-Channel MOSFET

FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g Tested



APPLICATIONS

- For Mobile Computing
 - Load Switch
 - Notebook Adaptor Switch
 - DC/DC Converter

| ABSOLUTE MAXIMUM RATIN | IGS (T _A = 25 °C | , unless othe | rwise noted) | |
|--|------------------------------------|-----------------------------------|----------------------|------|
| Parameter | | Symbol | Limit | Unit |
| Drain-Source Voltage | | V _{DS} | - 30 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current (T _J = 150 °C) | T _C = 25 °C | | - 5.6 | |
| | T _C = 70 °C | 1 , [| - 5.1 | |
| | T _A = 25 °C | | - 5.4 ^{b,c} | |
| | T _A = 70 °C | 1 | - 4.3 ^{b,c} | A |
| Pulsed Drain Current (t = 100 μs) | | I _{DM} | - 18 | |
| Continous Source-Drain Diode Current | T _C = 25 °C | I. | - 2.1 | |
| | T _A = 25 °C | I _S | - 1 ^{b,c} | |
| | T _C = 25 °C | | 2.5 | |
| Maximum Power Dissipation | T _C = 70 °C | | 1.6 | w |
| | T _A = 25 °C | P _D | 1.25 ^{b,c} | VV |
| | T _A = 70 °C | 1 | 0.8 ^{b,c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|--|--------------|-------------------|---------|---------|------|--|--|
| Parameter | | Symbol | Typical | Maximum | Unit | | |
| Maximum Junction-to-Ambient ^{b,d} | t ≤ 5 s | R _{thJA} | 75 | 100 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 40 | 50 | C/VV | | |

Notes:

- a. Based on T_C = 25 °C. b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 166 °C/W.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|-------------------------|--|-------|-------|----------|-------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$ | - 30 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | J 250A | | - 19 | | 1400 | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = - 250 μA | | 4 | | mV/°C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_{D} = -250 \mu\text{A}$ | - 0.5 | | - 2.0 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| | I _{DSS} | V _{DS} = - 30 V, V _{GS} = 0 V | | | - 1 | μA | |
| Zero Gate Voltage Drain Current | | V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C | | | - 5 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$ | - 2.5 | | | Α | |
| | . , | V _{GS} =- 10 V, I _D = - 4.4 A | | 0.046 | | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} =- 6 V, I _D = - 4 A | | 0.049 | | Ω | |
| | , , | V _{GS} =- 4.5 V, I _D = - 3.6 A | | 0.054 | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 3.4 A | | 18 | | S | |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | | 1295 | | | |
| Output Capacitance | C _{oss} | V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz | | 150 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 130 | | | |
| · | | V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 5.4 A | | 24 | 36 | | |
| Total Gate Charge | Q_g | | | 11.4 | 17 | nC | |
| Gate-Source Charge | Q _{gs} | V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 5.4 A | | 3.4 | | | |
| Gate-Drain Charge | Q _{gd} | 1 | | 3.8 | | | |
| Gate Resistance | R_g | f = 1 MHz | 1.5 | 7.7 | 15.4 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 13 | 20 | | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 3.5 \Omega$ | | 4 | 8 | _ | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -4.3 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$ | | 38 | 57 | | |
| Fall Time | t _f | 1 | | 6 | 12 | 1 | |
| Turn-On Delay Time | t _{d(on)} | | | 28 | 42 | ns | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V, R}_{L} = 3.5 \Omega$ | | 16 | 24 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -4.3 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$ | | 30 | 45 | | |
| Fall Time | t _f | 1 | | 10 | 20 | | |
| Drain-Source Body Diode Characteristic | s · | | | l | l | | |
| Continuous Source-Drain Diode Current | Is | T _C = 25 °C | | | - 2.1 | | |
| Pulse Diode Forward Current (t = 100 μs) | I _{SM} | | | | - 80 | A | |
| Body Diode Voltage | V _{SD} | I _S = - 4.3 A, V _{GS} = 0 V | | - 0.8 | - 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 15 | 23 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | 1 | | 7 | 14 | nC | |
| Reverse Recovery Fall Time | t _a | $I_F = -4.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | | 8 | | | |
| Reverse Recovery Rise Time | t _b | 1 | | 7 | <u> </u> | ns | |

Notes

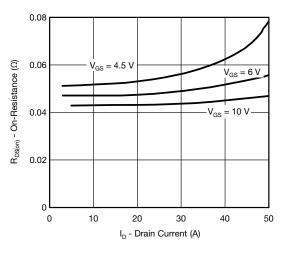
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

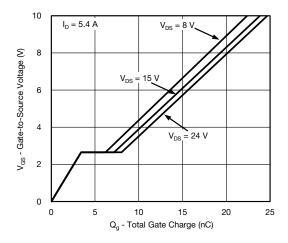




Output Characteristics



On-Resistance vs. Drain Current



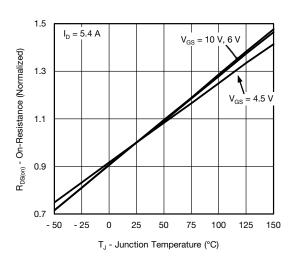
Gate Charge



Transfer Characteristics

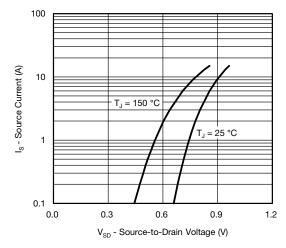


Capacitance

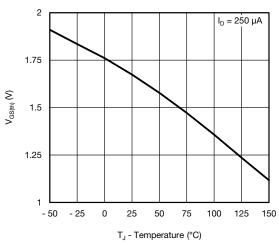


On-Resistance vs. Junction Temperature

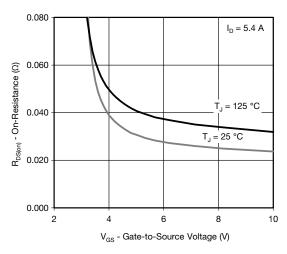




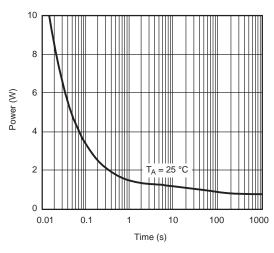
Source-Drain Diode Forward Voltage



Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power (Junction-to-Ambient)

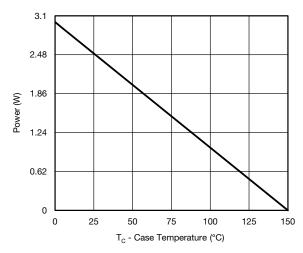


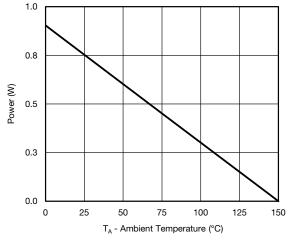
Safe Operating Area, Junction-to-Ambient





Current Derating*



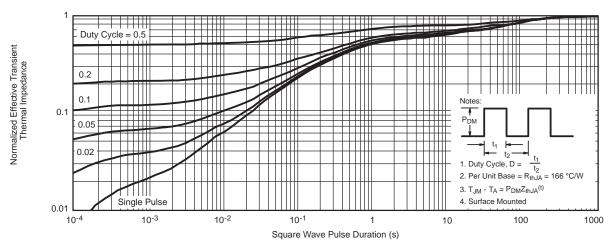


Power, Junction-to-Foot

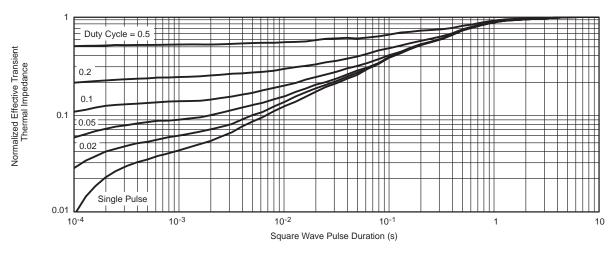
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





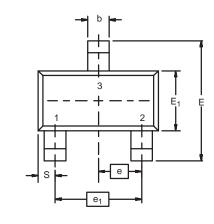
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







| Min 0.89 0.01 | Max 1.12 | Min 0.035 | Max | |
|---------------------|---|--|---|--|
| 0.01 | | 0.035 | 0.044 | |
| | | | 0.044 | |
| | 0.10 | 0.0004 | 0.004 | |
| 0.88 | 1.02 | 0.0346 | 0.040 | |
| 0.35 | 0.50 | 0.014 | 0.020 | |
| 0.085 | 0.18 | 0.003 | 0.007 | |
| 2.80 | 3.04 | 0.110 | 0.120 | |
| 2.10 | 2.64 | 0.083 | 0.104 | |
| 1.20 | 1.40 | 0.047 | 0.055 | |
| 0.95 BSC | | 0.0374 Ref | | |
| 1.90 BSC | | 0.0748 Ref | | |
| 0.40 | 0.60 | 0.016 | 0.024 | |
| 0.64 Ref | | 0.025 Ref | | |
| 0.50 Ref | | 0.020 Ref | | |
| 3° | 8° | 3° | 8° | |
| | 0.085 2.80 2.10 1.20 0.95 1.90 0.40 0.64 | 0.085 0.18 2.80 3.04 2.10 2.64 1.20 1.40 0.95 BSC 1.90 BSC 0.40 0.60 0.64 Ref 0.50 Ref 3° 8° | 0.085 0.18 0.003 2.80 3.04 0.110 2.10 2.64 0.083 1.20 1.40 0.047 0.95 BSC 0.0374 1.90 BSC 0.0748 0.40 0.60 0.016 0.64 Ref 0.025 0.50 Ref 0.020 3° 8° 3° | |

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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